Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-24. (Canceled)

25. (Previously presented) A method for producing a solar cell module, comprising:

providing a solar cell element having a front surface electrode formed on a light-receiving surface of a semiconductor substrate thereof, and a back surface electrode formed on a non-light receiving surface of the semiconductor substrate;

connecting a first inner lead to the front surface electrode or the back surface electrode of the solar cell element, by melting a first solder layer that is disposed therebetween, wherein the first inner lead comprises a metal foil; and

connecting a second inner lead to an electrode of the solar cell element to which the first inner lead is not connected, by melting the second solder layer that is disposed therebetween and has a lower melting point than the first solder layer, after performing the above connecting the first inner lead, wherein the second inner lead comprises a metal foil.

26. (Previously presented) The method for producing a solar cell module according to claim 25, wherein the first solder layer is substantially free of lead.

27. (Previously presented) The method for producing a solar cell module according to claim 25, wherein the first or the second inner lead is provided with a through hole at a connection area between the inner lead and the front surface electrode or the back surface electrode.

28. (Previously presented) The method for producing a solar cell module according to claim 25, wherein the inner leads are connected to a common connection line by means of a solder, and the inner leads are provided with through holes at connection areas between the inner leads and the common connection line.

29. (Previously presented) The method for producing a solar cell module according to claim 25, wherein the inner leads are connected to a common connection line by means of a solder, and the common connection line is provided with through holes at connection areas between the common connection line and the inner leads.

30. (Previously presented) The method for producing a solar cell module according to claim 25, wherein output wires connected to the solar cell elements are connected to terminals of a terminal box by means of a solder, and the output wires are provided with through holes at connection areas between the output wires and the terminals.

31. (Previously presented) The method for producing a solar cell module according to claim 25, wherein output wires connected to the solar cell elements are connected to terminals of a terminal box by means of a solder, and the terminals are provided with through holes at connection areas between the terminals and the output wires.

32. (Previously presented) The method for producing a solar cell module according to claim 25, further comprising coating a surface of the electrode with the solder layer before connecting a first connection tab to the front surface electrode or the back surface electrode of the solar cell element, through a first solder layer; and connecting a second inner lead to an electrode of the solar cell element to which the first inner lead is not connected, through the second solder layer having a lower melting point than the first solder layer, after performing the above connecting the first inner lead.

33. (Previously presented) The method for producing a solar cell module according to claim 25, further comprising coating a surface of the inner lead with the solder layer before connecting a first inner lead to the front surface electrode or the back surface electrode of the solar cell element, through a first solder layer; and connecting a second inner lead to an electrode of the solar cell element to which the first inner lead is not connected, through the second solder layer having a lower melting point than the first solder layer, after performing the above connecting the first inner lead.